



P3161956A2: WIRING BOARD FOR LOADING SEMICONDUCTOR ELEMENT AND MANUFACTURE THEREOF

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Kind:

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Abstract: **Purpose:** To improve a high density wiring and heat-dissipating properties by forming a conducting circuit and a wire bonding section while leaving the required section of a metallic film on the surface of a substrate.
Constitution: A recessed section 6 having a flat base is shaped at the central section of an aluminum nitride substrate 1, through-hole 2 are formed outside the recessed section 6, an oxide film is removed through activation treatment, and the film of copper is shaped through electrolytic copper plating by using a soft etchant. The whole surface on the copper film is coated with a photo-resist film, a negative film, to which a transparent section is shaped in the same form as a continuity circuit, is stuck onto the top face of the photo-resist film, the photo-resist film is cured through exposure, the negative film is removed, the photo-resist film in an unexposed section is removed, and the unnecessary copper film is taken off. The photo-resist film is peeled, and the continuity circuit 3 is formed. Land sections and wire bonding sections are shaped to the specified sections of the circuit 3, nail head pins 5 made of an alloy are inserted and fixed into the holes 2, and the insides of the holes 2 are hermetically sealed.
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Other Abstract Info: **DERABS G91-248899 DERG91-248899**

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